

ABSTRACT OF THE DISCLOSURE

An integrated circuit package for an image sensor chip includes an integrated heater element. In one embodiment, the integrated circuit package includes a substrate including a first surface disposed to receive an image sensor chip and a second surface having an array of contact terminals formed thereon and a heater element. The heater element has a first terminal and a second terminal coupled to a first contact terminal and a second contact terminal. The heater element is positioned on the first surface of the substrate and underneath the sensor area of the image sensor chip to be assembled in the package. The heater element provides heating of the sensor area of the image sensor chip when a first voltage is applied across the first contact terminal and the second contact terminal. An ESD protection resistor can be coupled between the first terminal and the second terminal of the heater element.